

## LM185QML Adjustable Micropower Voltage References

Check for Samples: [LM185QML](#)

### FEATURES

- Adjustable from 1.24V to 5.30V
- Operating Current of 10 $\mu$ A to 20mA
- 1 $\Omega$  Dynamic Impedance
- Low Temperature Coefficient

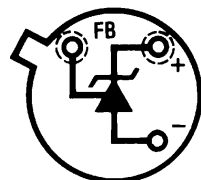
### DESCRIPTION

The LM185 are micropower 3-terminal adjustable band-gap voltage reference diodes. Operating from 1.24 to 5.3V and over a 10 $\mu$ A to 20mA current range, they feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming is used to provide tight voltage tolerance. Since the LM185 band-gap reference uses only transistors and resistors, low noise and good long-term stability result.

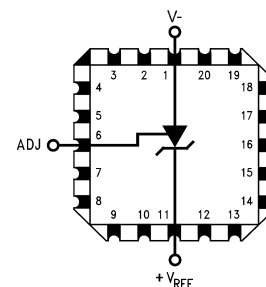
Careful design of the LM185 has made the device tolerant of capacitive loading, making it easy to use in almost any reference application. The wide dynamic operating range allows its use with widely varying supplies with excellent regulation.

The extremely low power drain of the LM185 makes it useful for micropower circuitry. This voltage reference can be used to make portable meters, regulators or general purpose analog circuitry with battery life approaching shelf life. Further, the wide operating current allows it to replace older references with a tighter tolerance part.

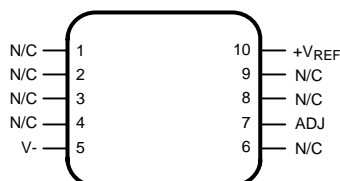
### Connection Diagrams



**Figure 1. PFM Metal Can Package (Bottom View)**  
See Package Number NDV0003H



**Figure 2. 20-Leadless Chip Carrier (Top View)**  
See Package Number NAJ0020A



**Figure 3. 10-Lead CLGA (Top View)**  
See Package Number NAC0010A



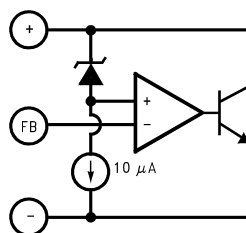
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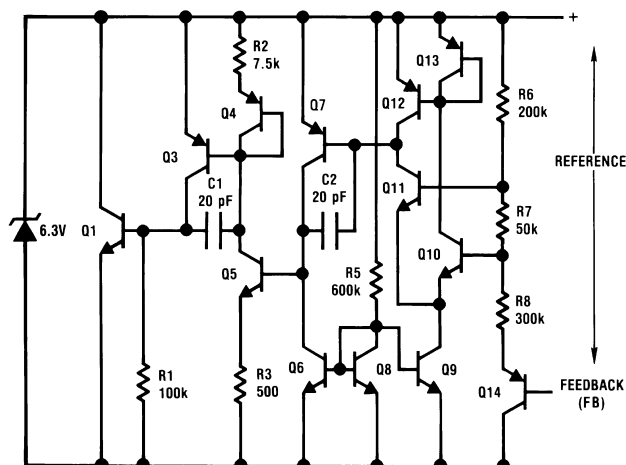
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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## Block Diagram



## Schematic Diagram



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**Absolute Maximum Ratings<sup>(1)</sup>**

Reverse Current			30mA
Forward Current			10mA
Operating Temperature Range			-55°C ≤ T <sub>A</sub> ≤ 125°C
Storage Temperature			-55°C ≤ T <sub>A</sub> ≤ 150°C
Maximum Junction Temperature T <sub>Jmax</sub>			150°C
Lead Temperature (soldering, 10 seconds)			300°C
Thermal Resistance	θ <sub>JA</sub>	LCCC Package (Still Air)	100°C/W
		LCCC Package (500LF/Min Air flow)	73°C/W
		Metal Can Package (Still Air)	300°C/W
		Metal Can Package (500LF/Min Air flow)	139°C/W
		CLGA Package (Still Air)	194°C/W
		CLGA Package (500LF/Min Air flow)	128°C/W
	θ <sub>JC</sub>	LCCC Package	25°C/W
		Metal Can Package	57°C/W
		CLGA Package	23°C/W
Package Weight (Typical)	LCCC Package	TBD	
	Metal Can Package	TBD	
	CLGA Package	210mg	
ESD Tolerance <sup>(2)</sup>			500V

(1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For guaranteed specifications and test conditions, see the Electrical Characteristics.

(2) Human body model, 1.5 k $\Omega$  in series with 100 pF.

**Table 1. Quality Conformance Inspection  
Mil-Std-883, Method 5005 - Group A**

Subgroup	Description	Temp °C
1	Static tests at	25
2	Static tests at	125
3	Static tests at	-55
4	Dynamic tests at	25
5	Dynamic tests at	125
6	Dynamic tests at	-55
7	Functional tests at	25
8A	Functional tests at	125
8B	Functional tests at	-55
9	Switching tests at	25
10	Switching tests at	125
11	Switching tests at	-55
12	Settling time at	25
13	Settling time at	125
14	Settling time at	-55

**LM185B Electrical Characteristics DC Parameters**

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
$V_{Ref}$	Reference Voltage	$I_R = 100\mu A$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$I_R = 9\mu A$		1.228	1.252	V	1
		$I_R = 10\mu A$		1.215	1.255	V	2, 3
		$I_R = 1mA$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$I_R = 20mA$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 100\mu A$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 45\mu A$		1.288	1.252	V	1
		$V_R = 5.3V, I_R = 50\mu A$		1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 1.0mA$		1.288	1.252	V	1
				1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 20mA$		1.288	1.252	V	1
				1.215	1.255	V	2, 3
$\Delta V_{Ref}/\Delta I_R$	Reference Voltage Change with Current	$9\mu A \leq I_R \leq 1mA$			1.0	mV	1
		$10\mu A \leq I_R \leq 1mA$			1.5	mV	2, 3
		$1mA \leq I_R \leq 20mA$			10	mV	1
					20	mV	2, 3
		$V_R = 5.3V, 45\mu A \leq I_R \leq 1mA$			1.0	mV	1
		$V_R = 5.3V, 50\mu A \leq I_R \leq 1mA$			1.5	mV	2, 3
		$V_R = 5.3V, 1mA \leq I_R \leq 20mA$			10	mV	1
					20	mV	2, 3
$\Delta V_{Ref} / \Delta V_O$	Reference Voltage Change with Output Voltage	$V_R = 5.3V, I_R = 100\mu A$			3.0	mV	1
					6.0	mV	2, 3
$I_F$	Feedback Current	$I_R = 9\mu A$			20	nA	1
		$I_R = 10\mu A$			25	nA	2, 3
		$I_R = 20mA$			20	nA	1
					25	nA	2, 3
		$V_R = 5.3V, I_R = 45\mu A$			20	nA	1
		$V_R = 5.3V, I_R = 50\mu A$			25	nA	2, 3
		$V_R = 5.3V, I_R = 20mA$			20	nA	1
					25	nA	2, 3
$I_C$	Minimum Operating Current	$V_R = V_{Ref}$	See <sup>(1)</sup>		9.0	$\mu A$	1
			See <sup>(1)</sup>		10	$\mu A$	2, 3
		$V_R = 5.3V$	See <sup>(1)</sup>		45	$\mu A$	1
			See <sup>(1)</sup>		50	$\mu A$	2, 3

(1) Functional test.

**LM185BY Electrical Characteristics DC Parameters**

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
V <sub>Ref</sub>	Reference Voltage	I <sub>R</sub> = 100μA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		I <sub>R</sub> = 9μA		1.228	1.252	V	1
		I <sub>R</sub> = 10μA		1.215	1.255	V	2, 3
		I <sub>R</sub> = 1mA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		I <sub>R</sub> = 20mA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 100μA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 45μA		1.288	1.252	V	1
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 50μA		1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 1.0mA		1.288	1.252	V	1
				1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 20mA		1.288	1.252	V	1
				1.215	1.255	V	2, 3
ΔV <sub>Ref</sub> /ΔI <sub>R</sub>	Reference Voltage Change with Current	9μA ≤ I <sub>R</sub> ≤ 1mA			1.0	mV	1
		10μA ≤ I <sub>R</sub> ≤ 1mA			1.5	mV	2, 3
		1mA ≤ I <sub>R</sub> ≤ 20mA			10	mV	1
					20	mV	2, 3
		V <sub>R</sub> = 5.3V, 45μA ≤ I <sub>R</sub> ≤ 1mA			1.0	mV	1
		V <sub>R</sub> = 5.3V, 50μA ≤ I <sub>R</sub> ≤ 1mA			1.5	mV	2, 3
		V <sub>R</sub> = 5.3V, 1mA ≤ I <sub>R</sub> ≤ 20mA			10	mV	1
					20	mV	2, 3
ΔV <sub>Ref</sub> / ΔV <sub>O</sub>	Reference Voltage Change with Output Voltage	V <sub>R</sub> = 5.3V, I <sub>R</sub> = 100μA			3.0	mV	1
					6.0	mV	2, 3
I <sub>F</sub>	Feedback Current	I <sub>R</sub> = 9μA			20	nA	1
		I <sub>R</sub> = 10μA			25	nA	2, 3
		I <sub>R</sub> = 20mA			20	nA	1
					25	nA	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 45μA			20	nA	1
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 50μA			25	nA	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 20mA			20	nA	1
					25	nA	2, 3
I <sub>C</sub>	Minimum Operating Current	V <sub>R</sub> = V <sub>Ref</sub>	See <sup>(1)</sup>		9.0	μA	1
			See <sup>(1)</sup>		10	μA	2, 3
		V <sub>R</sub> = 5.3V	See <sup>(1)</sup>		45	μA	1
			See <sup>(1)</sup>		50	μA	2, 3
T <sub>C</sub>	Temperature Coefficient		See <sup>(2)</sup>		50	PPM/°C	1, 2, 3

(1) Functional test.

(2) The average temperature coefficient is defined as the maximum deviation of reference voltage, at all measured temperatures between the operating T<sub>Min</sub> & T<sub>Max</sub>, divided by (T<sub>Max</sub> - T<sub>Min</sub>). The measured temperatures (T<sub>Measured</sub>) are -55°C, 25°C, & 125°C or ΔV<sub>Ref</sub> / (T<sub>Max</sub> - T<sub>Min</sub>)

## Typical Performance Characteristics

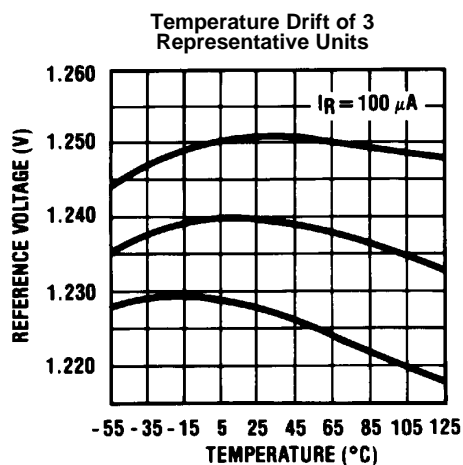


Figure 4.

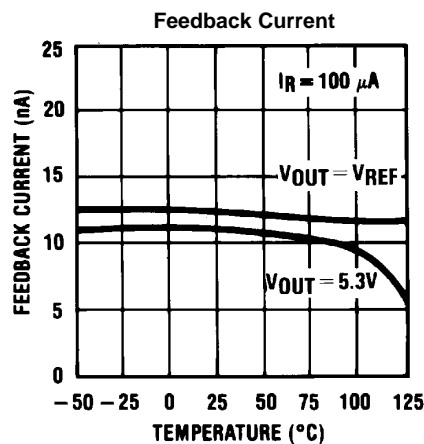


Figure 5.

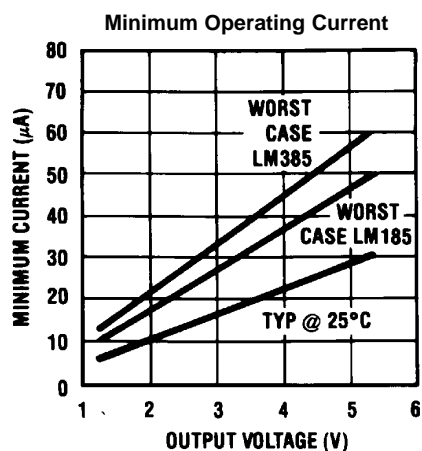


Figure 6.

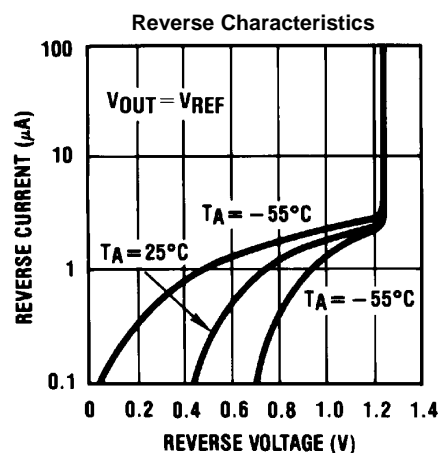


Figure 7.

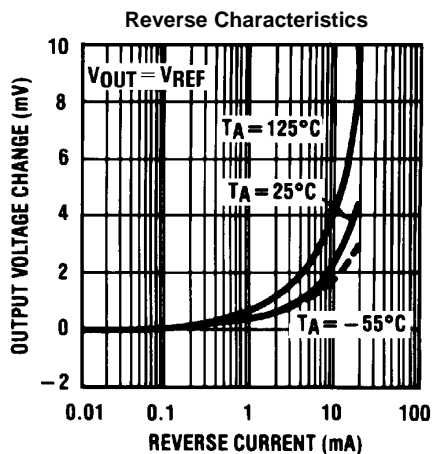


Figure 8.

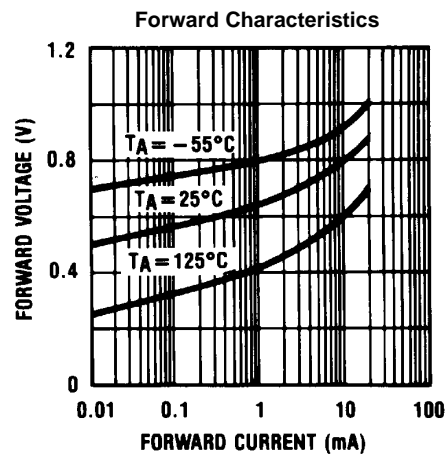


Figure 9.

# Typical Performance Characteristics (continued)

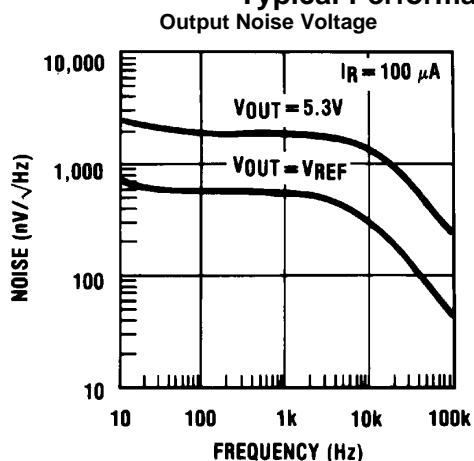


Figure 10.

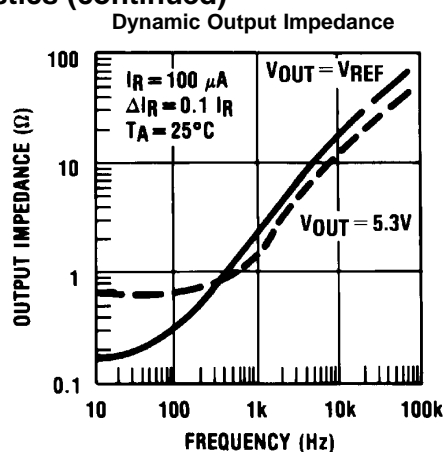


Figure 11.

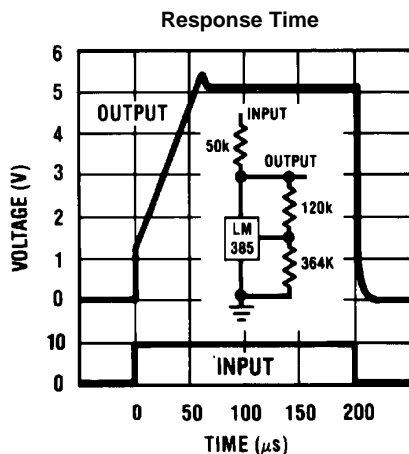


Figure 12.

## Temperature Coefficient Typical LM185

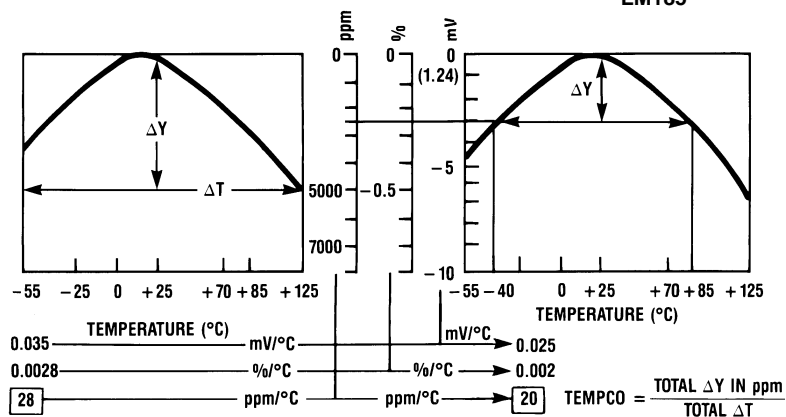
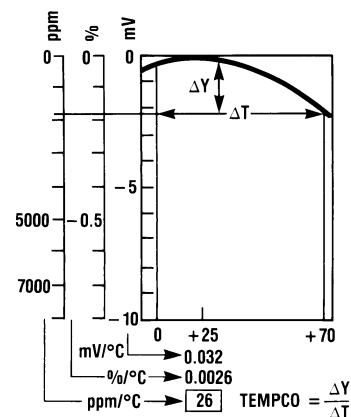
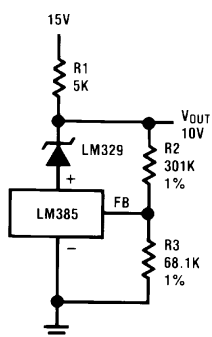


Figure 13.



### Precision 10V Reference



**Figure 14.**

**Figure 15.**

The circuit diagram shows a precision current source. A 100  $\mu\text{A}$  current source is connected to the non-inverting input of an LM385 precision centee-voltage reference. The LM385 is configured with its inverting input to ground and its output to a 25V output. The output is connected to a 120k resistor (R1) and a 2.4M resistor (R2). The 2.4M resistor is connected to the gate of a 2N5115 JFET. The JFET is configured as a source follower, with its source connected to ground and its drain connected to the 100  $\mu\text{A}$  current source. The JFET's gate is also connected to its drain through a feedback resistor (FB).

**Figure 16.**

**Figure 17.**

**Figure 18.**

5.1V TO 16V

VIN

R1 22k

R2 3k

R3 1M

R4 10K

R5 10k

R6 22k

R7 332k 1%

R8 1M 1%

C1 0.1  $\mu$ F

C2 500  $\mu$ F

HEAT SINK

2N2905

LM385

FB

2N3904

2N3904

$I_q = 70 \mu A$

$0 < I_{OUT} < 50 mA$

VOUT 5V

**Figure 19.**



Voltage Level Detector

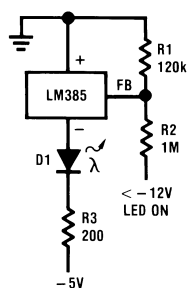


Figure 20.

Voltage Level Detector

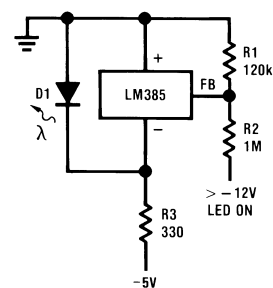


Figure 21.

Fast Positive Clamp  
 $2.4V + \Delta V_{D1}$

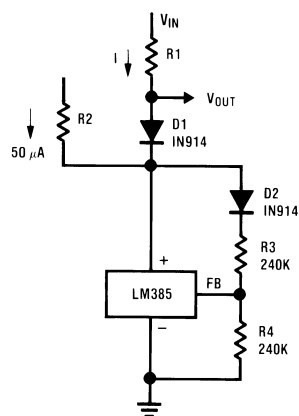


Figure 22.

Bidirectional Clamp  
 $\pm 2.4V$

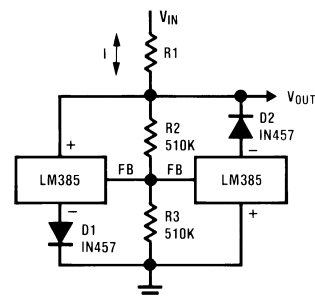


Figure 23.

Bidirectional Adjustable Clamp  
 $\pm 1.8V$  to  $\pm 2.4V$

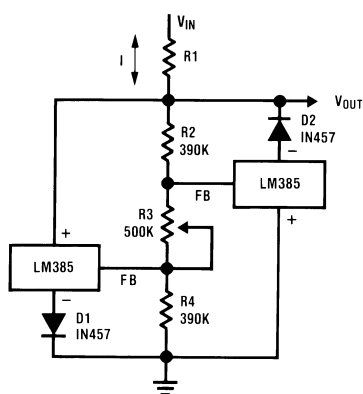


Figure 24.

Bidirectional Adjustable Clamp  
 $\pm 2.4V$  to  $\pm 6V$

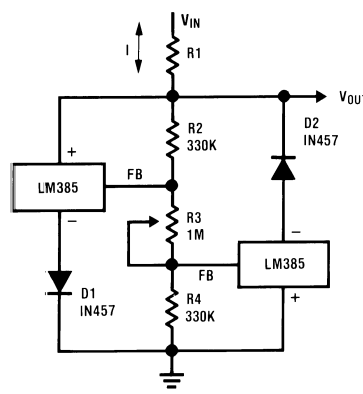
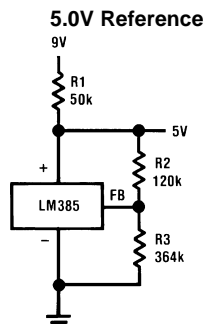


Figure 25.







**Figure 32.**

## REVISION HISTORY SECTION

Released	Revision	Section	Originator	Changes
11/08/05	A	New Release, Corporate format	L. Lytle	2 MDS data sheets converted into one Corp. data sheet format. MNLM185B-X Rev 0B0 and MNLM185BY-X Rev 0B0 will be archived.
04/06/06	B	Ordering Information Table, WG Connection Diagram, Absolute Maximum Ratings Section, Physical Dimensions Section	R. Malone	Added NSID, Connection Diagram, Physical Dimension Dwg, Thermal Resistance and Package Weight for NAC package. Revision A will be Archived.
06/12/08	C	LM185B and LM185BY Electrical Section	Larry McGee	Correct IC test, $V_R = V_{REF}$ condition, subgroup 1, 2, 3 moved limits to the maximum column. Revision B will be Archived.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-9091402QYA	ACTIVE	CLGA	NAC	10	54	TBD	Call TI	Call TI	-55 to 125	LM185BWG /883 Q 5962-90914 02QYA ACO 02QYA >T	
LM185BWG/883	ACTIVE	CLGA	NAC	10	54	TBD	Call TI	Call TI	-55 to 125	LM185BWG /883 Q 5962-90914 02QYA ACO 02QYA >T	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

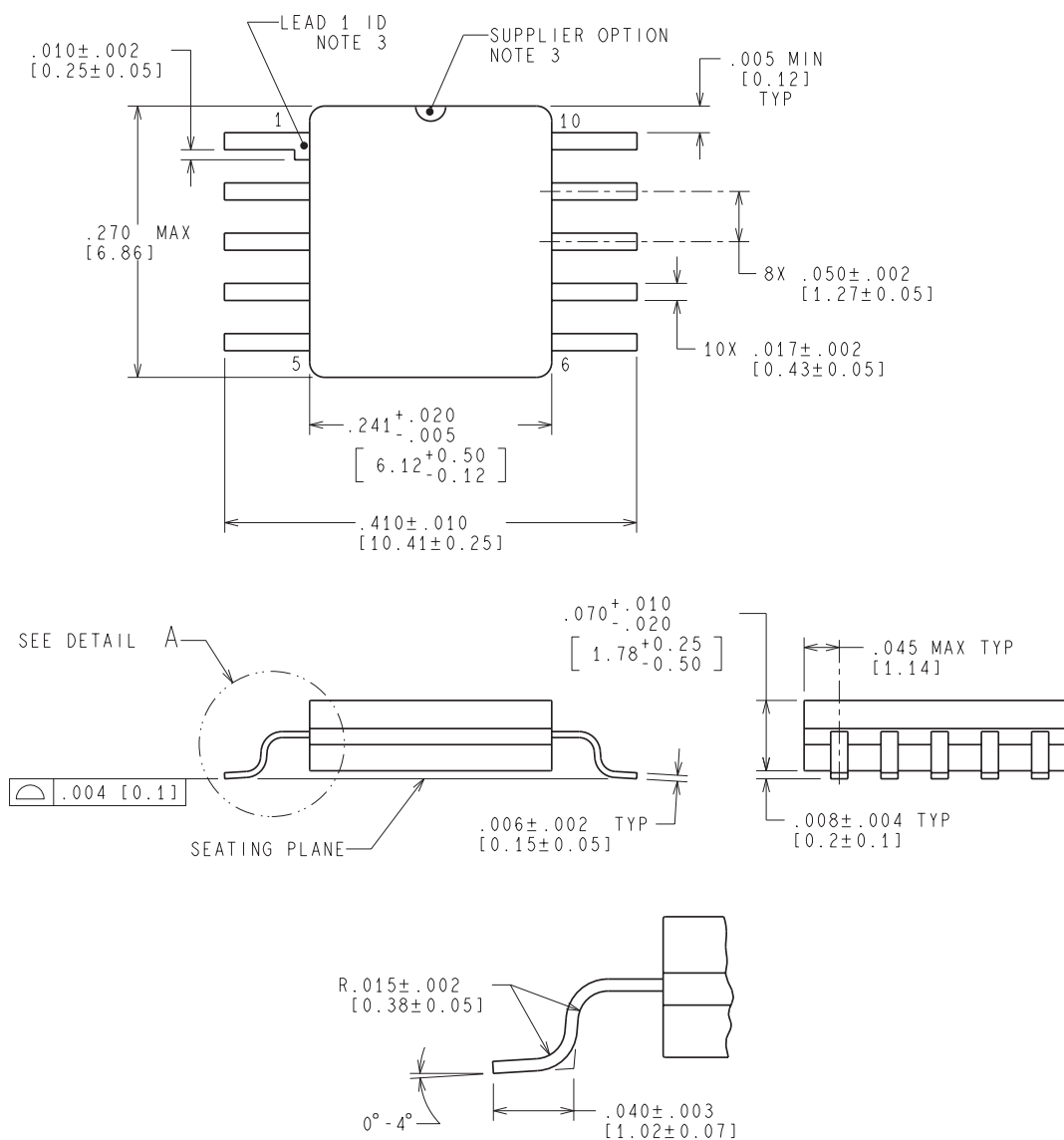
(4) Only one of markings shown within the brackets will appear on the physical device.

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NAC0010A



MIL-PRF-38535  
CONFIGURATION CONTROL

DETAIL A  
TYPICAL

WG10A (Rev H)

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